

# SEMICONDUCTOR MATERIALS



## MULTICORE® ACCURUS™ SOLDER MATERIALS

### SOLDER SPHERES

| ALLOY   | DIAMETER, mm | TOLERANCES ± mm | C <sub>pk</sub> | PACKAGE SIZE   |                 |             |
|---|--------------|-----------------|-----------------|----------------|-----------------|-------------|
|   |              |                 |                 | SPHERES/BOTTLE | BOTTLE SIZE, CC | SPHERES/BOX |
| <b>Sn-Ag-Cu Series</b><br>Sn96.5-Ag3.5<br>Sn-Ag1-Cu0.5<br>Sn-Ag2.6-Cu0.6<br>Sn-Ag3-Cu0.5*<br>Sn-Ag3.8-Cu0.7†<br>Sn-Ag4-Cu0.5† | 0.500        | 0.015           | 1.133           | 500,000        | 100             | 10,000,000  |
|   | 0.450        |                 |                 |                |                 |             |
|   | 0.406        |                 |                 |                |                 |             |
|   | 0.400        |                 |                 |                |                 |             |
|   | 0.350        |                 |                 |                |                 |             |
|   | 0.304        |                 |                 |                |                 |             |
| <b>Sn-Ag-Cu-Ni-Ge Series</b><br>Sn-Ag1-Cu0.5-Ni0.05-Ge††<br>Sn-Ag1.2-Cu0.5-Ni0.02-Ge††<br>Sn-Ag3-Cu0.5-Ni0.05-Ge††            | 0.300        | 0.010           | 1.133           | 1,000,000      | 40              | 20,000,000  |
|   | 0.250        |                 |                 |                |                 |             |
|   | 0.200        |                 |                 |                |                 |             |
|   | 0.180        |                 |                 |                |                 |             |
| <b>CASTIN Series</b><br>CASTIN125®‡<br>CASTIN258®‡<br>CASTIN305®‡   | 0.150        | 0.005           | 1.133           | 1,000,000      | 25              | 20,000,000  |
|   | 0.100        |                 |                 |                |                 |             |
|   | 0.080        |                 |                 |                |                 |             |
| <b>Sn-Zn Series</b><br>Sn91-Zn9<br>Sn-Zn8-Ag0.5-Al0.01-Ga0.1  | 0.080        | 0.005           | 1.133           | 1,000,000      | 10              | 20,000,000  |
|   | 0.050        |                 |                 |                |                 |             |

Patent No: †SURF-U.S. 5,527,628 \*SENJU-JP3,027,441 †AIM-U.S.5,352,407 U.S.5,405,577 JP2,752,258 ††FUJI-U.S.6,179,935 JP3,296,289 Other alloys and sizes are available upon request.

### TACKY FLUXES

| PRODUCT | DESCRIPTION                                | APPLICATION   | VISCOSITY | COLOR            | TACK, g/mm <sup>2</sup> | ACID VALUE | SOLIDS CONTENT, % | IPC/J-STD-004 CLASSIFICATION |
|---------|--|---|-----------|------------------|-------------------------|------------|-------------------|------------------------------|
| TFN600™ | Standard viscosity; no clean tacky flux.   | Printing (screen and stencil); pin transfer and dispensing. | 300,000   | Brown            | 130                     | 76         | 49                | ROLO                         |
| TFN610™ | Low viscosity; no clean tacky flux.        | Spraying, jetting and dipping.                              | 25,000    | Very Pale Yellow | 133                     | 116        | 66                | ROLO                         |
| WS300™  | Standard viscosity; water wash tacky flux. | Printing (screen and stencil); pin transfer and dispensing. | 550,000   | Brown            | 132                     | 30         | 80                | ORH1                         |

### WAFER BUMPING SOLDER PASTE

| PRODUCT | DESCRIPTION  | ALLOY                          | % METAL LOADING | TACK, g/mm <sup>2</sup> | PRINT SPEED, mm/s | REFLOW ATMOSPHERE | IPC/J-STD-004 CLASSIFICATION |
|---------|--|--------------------------------|-----------------|-------------------------|-------------------|-------------------|------------------------------|
| WS300™  | A water wash flux system specially formulated with fine-powder lead-free alloys. High performance, water-washable solder paste. Residues are easily removed with DI water without the need for a saponifier. Good open time with excellent print definition and soldering. | 96SC (SAC387)<br>97SC (SAC305) | 89              | 0.8                     | 25 - 100          | N <sup>2</sup>    | ORH1                         |

